

sink 110 prior to encapsulation (step 1130) and align the heat sink 110 above the semiconductor die 130.

IN THE ABSTRACT

Please replace the abstract with the following:

The present invention relates to an integrated circuit package having a semiconductor die electrically connected to a substrate, a heat sink having a portion thereof exposed to the surroundings of the package, a thermally conductive element thermally coupled to the semiconductor die and the heat sink, and an encapsulant material encapsulating the thermally conductive element and the heat sink such that a top and a side portion of the heat sink are exposed to the surroundings of the package.

IN THE CLAIMS

Please cancel claim 1.

Please replace claims 2-6, 8-10, 13, 20 and 21 with the following:

2. (One Time Amended) The integrated circuit package of claim 3, wherein said thermally conductive element is substantially shaped as a right rectangular solid.

3. (One Time Amended) An integrated circuit package, comprising:
a semiconductor die electrically connected to a substrate;
a heat sink having a portion thereof exposed to the surroundings of said package;
a thermally conductive element thermally coupled with and interposed between both said semiconductor die and said heat sink, wherein said thermally conductive element does not directly contact said semiconductor die; and

an encapsulant material encapsulating said thermally conductive element and said heat sink such that said portion of said heat sink is exposed to the surroundings of said package,